Device Material Content

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Package: **900 fpBGA**
Total Device Weight **4.10** **Grams**

Package Code: **FN900**
Products: LFSC

Assembly: ASEM
Size (mm): 31 x 31
Lead pitch (mm): 1.0
MSL: 3
Reflow max (°C): 250

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.64%	0.0672	1.64%	0.0672	Silicon chip	7440-21-3	100.00%	Die size: 9.49 x 9.80 mm
Mold Compound	41.74%	1.7113	2.09%	0.0856	Epoxy Resin	-	5.00%	Mold Compound: Hitachi CEL9750ZHF10AKL-U (ULA)
			2.09%	0.0856	Phenol Resin	-	5.00%	
			0.08%	0.0034	Carbon Black	1333-86-4	0.20%	
			36.65%	1.5026	Silica	60676-86-0	87.80%	
			0.83%	0.0342	Others	-	2.00%	
D/A Epoxy	0.23%	0.0094	0.18%	0.00756	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.05%	0.00189	Esters & resins	-	20.00%	
Wire	0.64%	0.0264	0.63%	0.0260	Gold (Au)	7440-57-5	98.50%	0.8 mil diameter; 1 wire per solder ball
Solder Balls	21.82%	0.8945	21.05%	0.8632	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.65%	0.0268	Silver (Ag)	7440-22-4	3.00%	
			0.11%	0.0045	Copper (Cu)	7440-50-8	0.50%	
Substrate	33.92%	1.3907	20.01%	0.8205	Laminate*	-	59.00%	BT Resin CCL-HL832NX-A
			4.81%	0.1971	Solder mask PSR4000 AUS 308	-	14.17%	
			7.46%	0.3060	Copper	7440-50-8	22.00%	
			1.37%	0.0563	Nickel plating	7440-02-0	4.05%	
			0.26%	0.0108	Gold plating	7440-57-5	0.78%	

Notes: * 0.20% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
Constituent substances and proportions in epoxy materials are before curing.
The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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